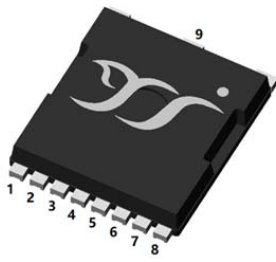
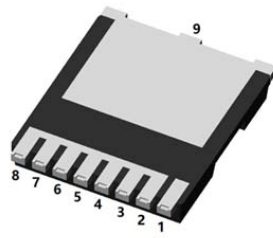


## N-Channel Enhancement Mode Field Effect Transistor

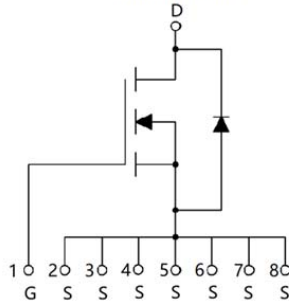


Top View



Bottom View

TOLL



### Product Summary

- $V_{DS}$  100V
- $I_D$  300A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ )  $< 1.7m\Omega$
- 100% EAS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free
- Part no. with suffix "Q" means AEC-Q101 qualified

### Applications

- High power inverter system
- Uninterruptible power supply
- LCDM appliances

### ■ Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		$V_{DS}$	100	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current	$T_A=25^\circ C$	$I_D$	23	A
	$T_A=100^\circ C$		16	
	$T_C=25^\circ C$		300	
	$T_C=100^\circ C$		212	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	900	A
Avalanche energy <sup>B</sup>		EAS	2116	mJ
Total Power Dissipation <sup>C</sup>	$T_A=25^\circ C$	$P_D$	3.3	W
	$T_A=100^\circ C$		1.6	
	$T_C=25^\circ C$		375	
	$T_C=100^\circ C$		187	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+175	$^\circ C$

### ■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient <sup>D</sup>	Steady-State	$R_{\theta JA}$	38	45	$^\circ C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	0.25	0.5	

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJT300G10AQ	F1	YJT300G10A	2000	4000	20000	13" reel



# YJT300G10AQ

## ■ Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2	2.6	4	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	1.35	1.7	mΩ
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =30A, V <sub>GS</sub> =0V	-	0.8	1.3	V
Gate resistance	R <sub>G</sub>	f=1MHz	-	1.35	-	Ω
Maximum Body-Diode Continuous Current	I <sub>S</sub>		-	-	300	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=100KHz	-	10411	-	pF
Output Capacitance	C <sub>oss</sub>		-	1986	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	24.7	-	
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =50V, I <sub>D</sub> =30A	-	166	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	34	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	49	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =30A, di/dt=100A/us	-	167	-	nC
Reverse Recovery Time	t <sub>rr</sub>		-	92	-	ns
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> =50V, I <sub>D</sub> =30A R <sub>GEN</sub> =4.5Ω	-	30	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	65	-	
Turn-off Delay Time	t <sub>D(off)</sub>		-	121	-	
Turn-off fall Time	t <sub>f</sub>		-	65	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=2mH, I<sub>AS</sub>=46A.

C. P<sub>d</sub> is based on max. junction temperature, using junction-case thermal resistance.

D. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in the still air environment with T<sub>A</sub>=25°C. The maximum allowed junction temperature of 175°C. The value in any given application depends on the user's specific board design.



# YJT300G10AQ

## Typical Electrical and Thermal Characteristics Diagrams

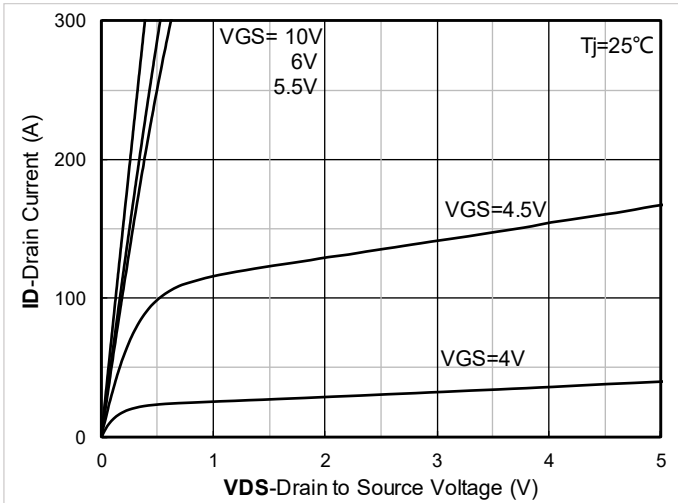


Figure 1. Output Characteristics

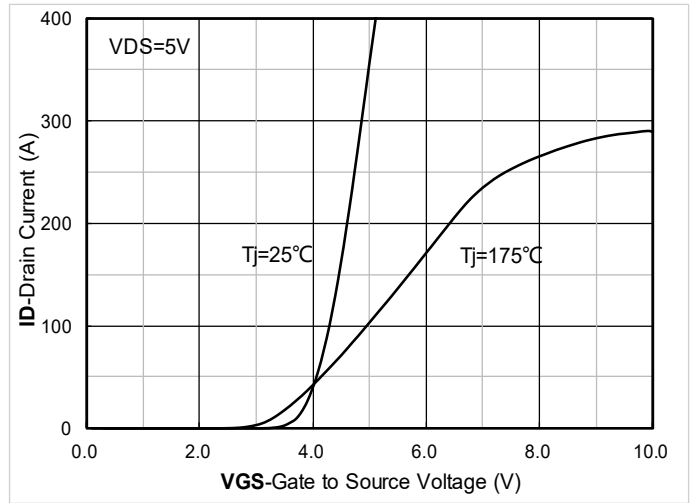


Figure 2. Transfer Characteristics

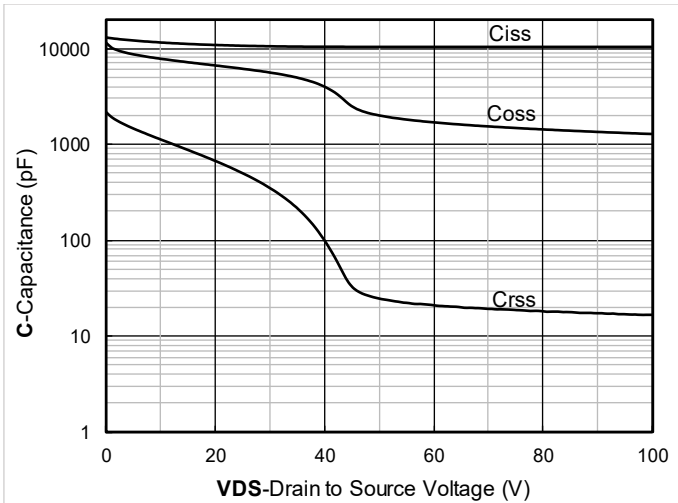


Figure 3. Capacitance Characteristics

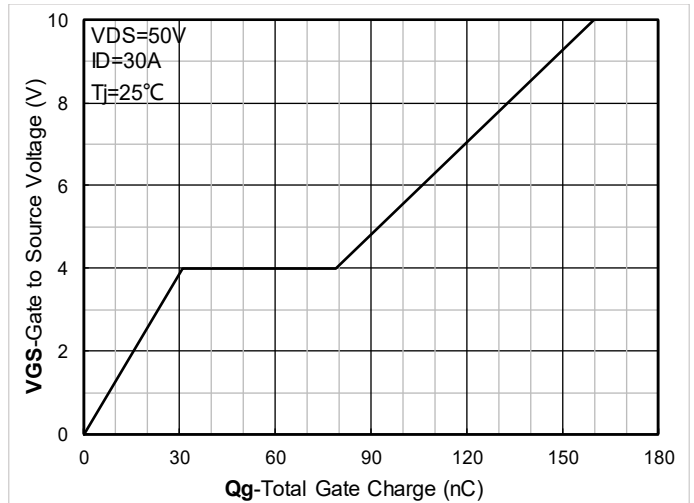


Figure 4. Gate Charge

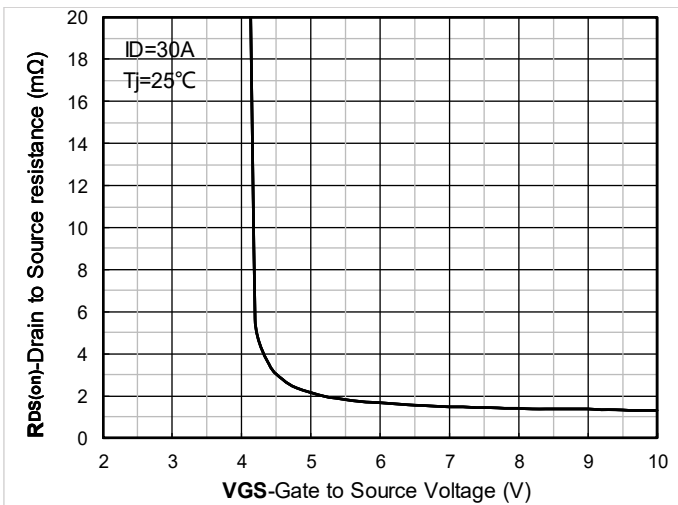


Figure 5. On-Resistance vs Gate to Source Voltage

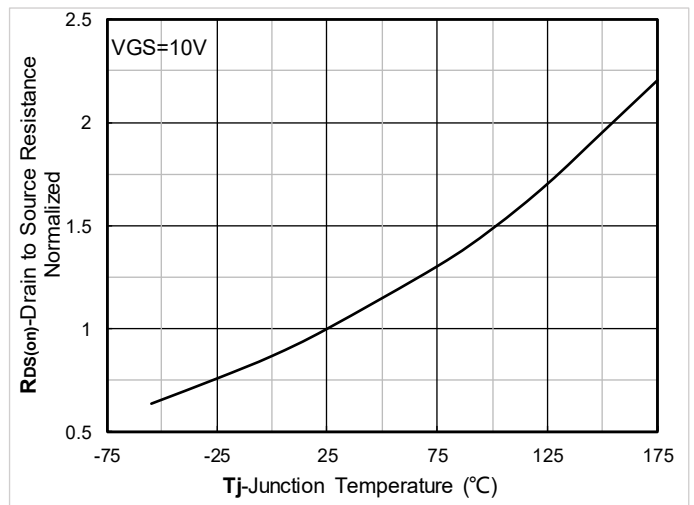


Figure 6. Normalized On-Resistance



# YJT300G10AQ

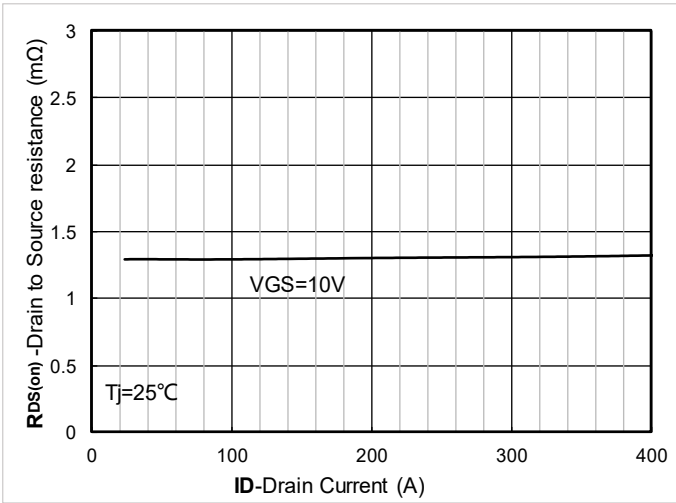


Figure 7. RDS(on) VS Drain Current

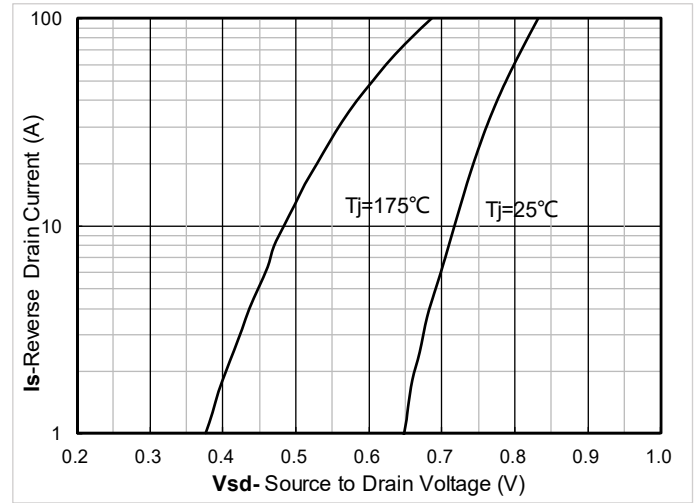


Figure 8. Forward characteristics of reverse diode

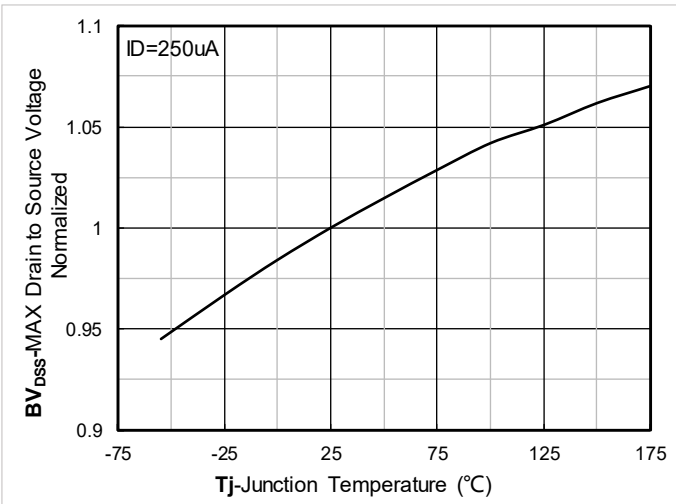


Figure 9. Normalized breakdown voltage

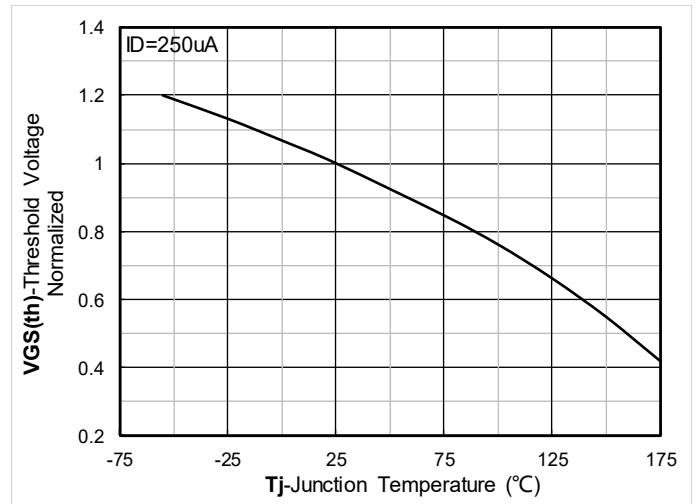


Figure 10. Normalized Threshold voltage

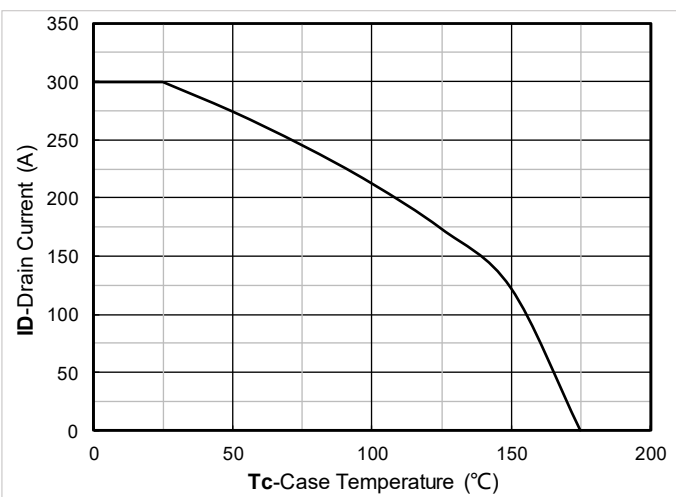


Figure 11. Current dissipation

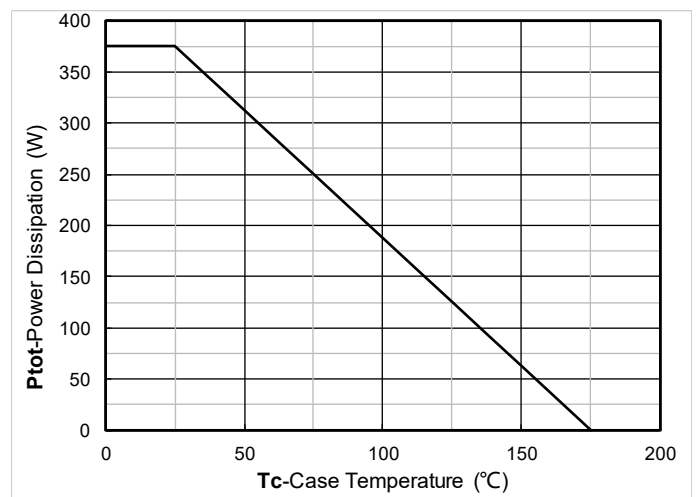


Figure 12. Power dissipation

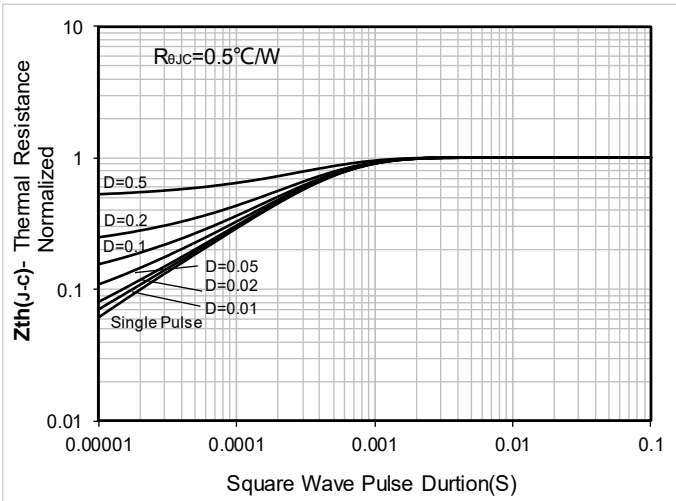


Figure 13. Maximum Transient Thermal Impedance

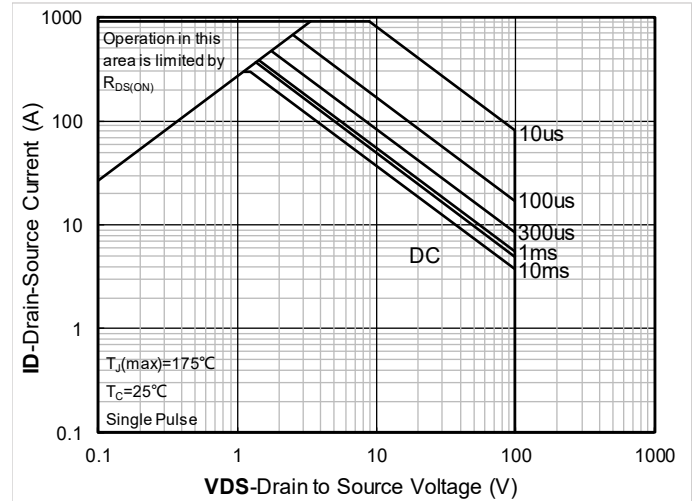


Figure 14. Safe Operation Area

## ■ Test Circuits & Waveforms

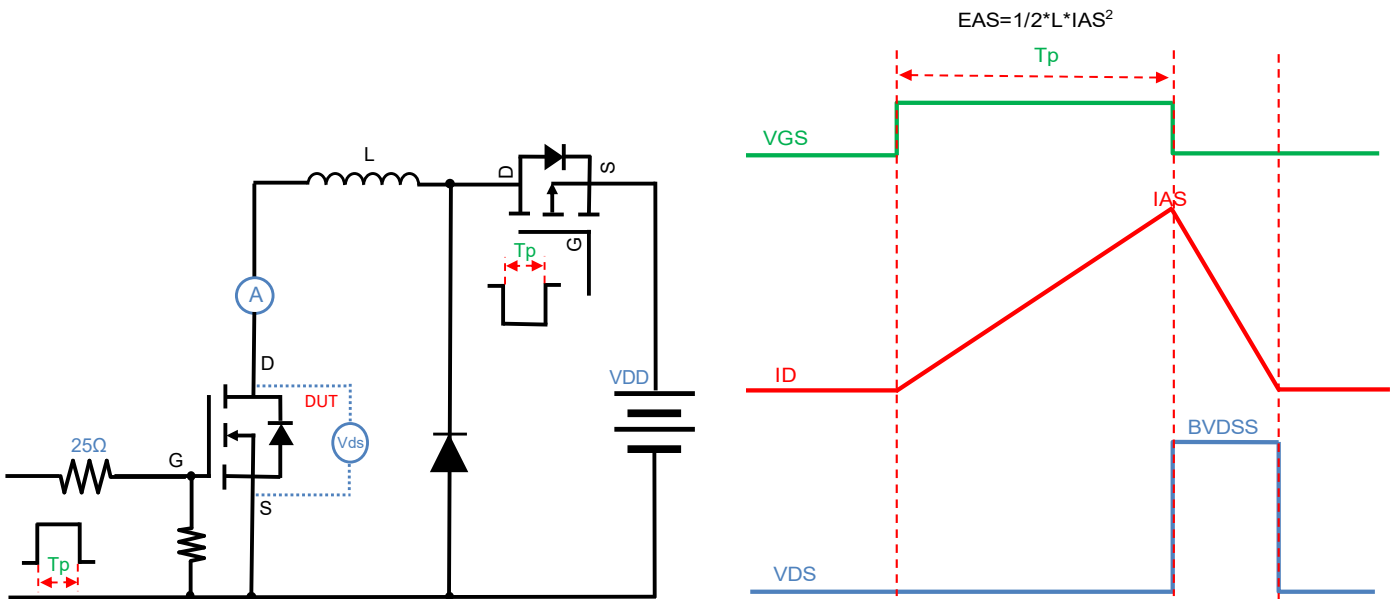


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

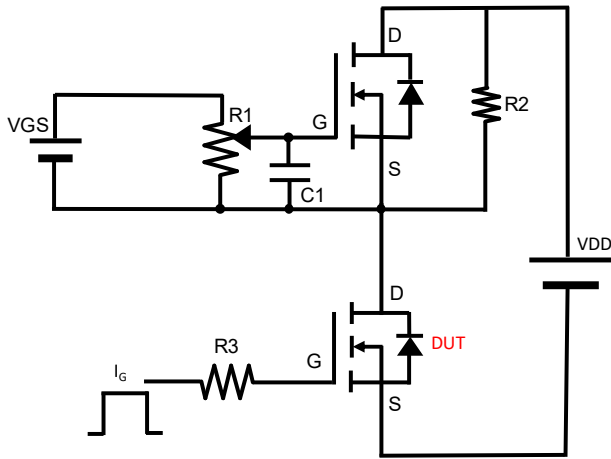


Figure B. Gate Charge Test Circuit & Waveform

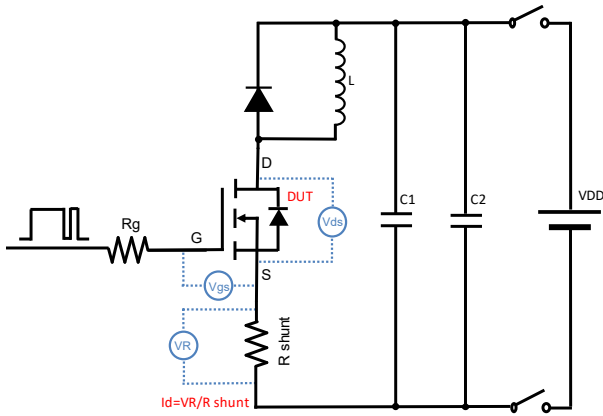


Figure C. Resistive Switching Test Circuit & Waveform

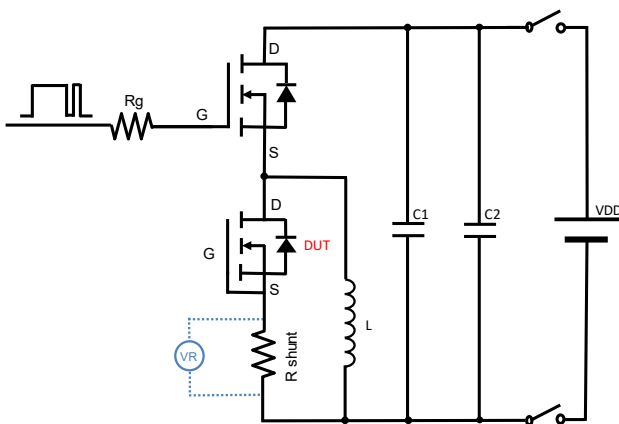
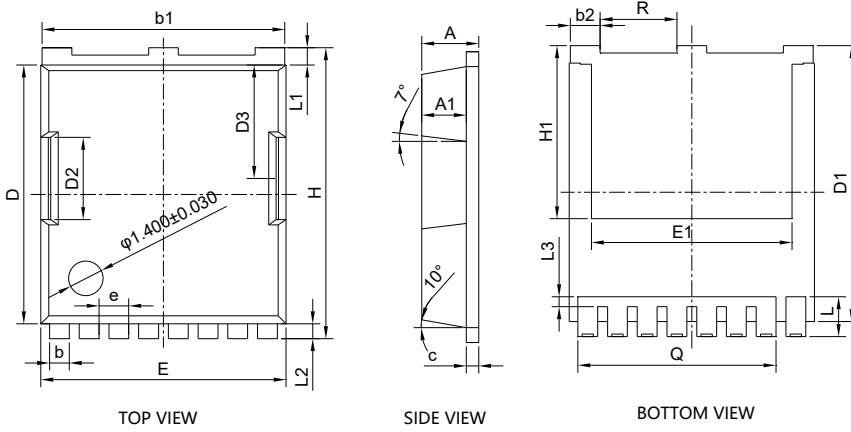


Figure D. Diode Recovery Test Circuit & Waveform



# YJT300G10AQ

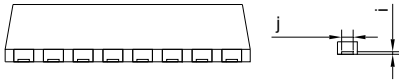
## ■ TOLL Package information



TOP VIEW

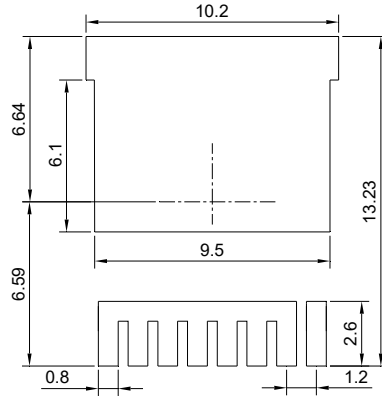
SIDE VIEW

BOTTOM VIEW



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.03\text{mm}$ .
3. The pad layout is for reference purposes only.



SUGGESTED SOLDER PAD LAYOUT

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.2	2.3	2.4
A1	1.7	1.8	1.9
b	0.7	0.8	0.9
b1	9.7	9.8	9.9
b2	1.1	1.2	1.3
c	0.4	0.5	0.6
D	10.28	10.38	10.48
D1	10.98	11.08	11.18
D2	3.2	3.3	3.4
D3	4.45	4.55	4.65
E	9.8	9.9	10
E1	8	8.1	8.2
e	1.2 BSC		
H	11.58	11.68	11.78
H1	6.95 BSC		
i	0.1 REF		
j	0.46 REF		
L	1.5	1.6	1.7
L1	0.6	0.7	0.8
L2	0.5	0.6	0.7
L3	0.3	0.4	0.5
Q	8 REF		
R	3.0	3.1	3.2

UNIT: mm



# YJT300G10AQ

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